

REMARKS

The rejection of claims 1, 5-7, 9-11, 15-17, 19 and 20 under 35 USC 103(a) as being unpatentable over the prior art shown in Fig. 4 and described in the specification on pages 1-2 in combination with Chen et al (USP 6,686,667) is respectfully traversed.

The Examiner has indicated that claims 2-4, 8, 12-14 and 18 are allowable provided they are rewritten in independent form including all of the limitations of the base claim from which they depend and any intervening claims. Accordingly, applicant has amended claim 1 to incorporate the subject matter of claims 2 and 3 and has amended claim 11 to incorporate the subject matter of claims 12 and 13. In addition, applicant has amended claim 8 to depend from claim 1 and claim 18 to depend from claim 11. Claims 2-3 and 12-13 have been cancelled without prejudice.

Claim 1, as amended, includes the limitation originally in claim 2, that the chip carrier is formed with a through hole penetrating therethrough and that the first chip is mounted on the upper surface of the chip carrier and over the through hole. In addition, claim 1 has been amended to include the limitation of claim 3 having "at least one second chip attached to the first chip and received in the through hole of the carrier, such that the second chip is electrically connected to the lower surface of the chip carrier".

The same is true for claim 11 which has been amended to include the limitation of claim 12 reciting the chip carrier as being formed with a through hole penetrating therethrough and having a first chip mounted over the through hole and on the upper surface of the chip carrier. In addition, claim 11 requires the step of "attaching at least one second chip to the first chip and receiving the second chip in the through hole of the chip carrier, allowing the second chip to be electrically connected to the lower surface of the chip carrier" which limitation was taken directly from claim 13.

Accordingly, claims 1 and 11 are now believed to be patentable over the cited references.

Claims 2 and 3 have been cancelled and claims 4-10 are all now dependent upon claim 1. Likewise, claims 12 and 13 have been cancelled and claims 14-20 now depend from claim 11.

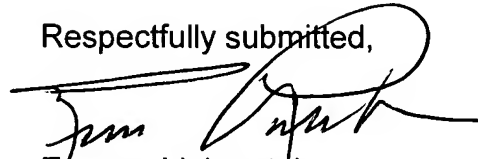
Applicants invention is directed to a light sensitive semiconductor package and a fabrication method thereof in which a chip is mounted on a chip carrier and encompassed by a dam and an infrared filter attached to the dam to hermetically isolate the chip from the atmosphere. The chip carrier has an upper surface and an opposite lower surface with a through hole penetrating through the entire chip carrier with the first chip mounted on the upper surface of the chip carrier and over the through hole and being electrically connected to the upper surface of the chip carrier and a second chip attached to the first chip and received in the through hole of the chip carrier such that the second chip is electrically connected to the lower surface of the chip carrier.

The semi-fabricated package is formed with chips hermetically isolated by the infrared filter and with the dam subject to a leak test before the encapsulant is formed so as to reduce fabrication costs and improve yield of the fabricated package.

Claims 1 and 11 as amended are clearly patentable over the cited features of applicants own prior art of Fig. 4 and Chen (USP 6,686,667).

Reconsideration and allowance of claims 1, 4-11 and 14-20, is respectfully requested.

Respectfully submitted,



Eugene Lieberstein
Reg. No. 24,645

ANDERSON, KILL & OLICK
1251 Avenue of the Americas
New York, New York 10020-1182
(212) 278-1000

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